

Product Change Notification - JAON-15OELO113

Date: 29 Jun 2016

Product Category: Memory; Analog (Thermal, Power Management & Safety); Analog (Linear & Mixed Signal) AND Interface; 8-bit Microcontrollers

Notification subject: CCB 2594 Final Notice: Qualification of CuPdAu bond wire in selected products of the 150K and 160K wafer technologies available in 8L MSOP package at MTAI assembly site.

Notification text: **PCN Status:**
Final notification

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 150K and 160K wafer technologies available in 8L MSOP package at MTAI assembly site.

Pre Change:

Gold (Au) bond wire

Post Change:

Palladium coated copper with gold flash (CuPdAu) bond wire

Pre and Post Change Summary:

	Pre Change	Post Change

Assembly Site	MTAI assembly site	MTAI assembly site
Wire material	Au wire	CuPdAu wire
Die attach material	8390A	8390A
Molding compound material	G600	G600
Lead frame material	CDA194	CDA194

Impacts to Data Sheet:

None

Reason for Change:

To improve manufacturability and qualify Palladium coated copper with gold flash (CuPdAu) bond wire.

Change Implementation Status:

In Progress

Estimated First Ship Date:

July 24, 2016 (date code: 1629)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	June 2016					July 2016			
Workweek	22	23	24	25	26	27	28	29	30
Initial PCN Issue Date		X							
Qual Report Availability					X				

Final PCN Issue Date					X				
Estimated Implementation Date								X	

Markings to Distinguish Revised from Unrevised Devices:

Traceability code

Revision History:

June 8, 2016: Issued initial notification.

June 29, 2016: Issued final notification. Attached the qualification report. Provided estimated first ship date. Updated the scope by removing selected products of the 250K wafer technology.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN_JAON-15OELO113_Qual_Report.pdf](#)

[PCN_JAON-15OELO113_Affected_CPN.pdf](#)

[PCN_JAON-15OELO113_Affected_CPN.xls](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

PCN_JAON-15OELO113
CATALOG_PART_NBR
24AA01-I/MS
24AA01T-I/MS
24AA02-I/MS
24AA02T-I/MS
24AA044-E/MS
24AA044-I/MS
24AA044T-E/MS
24AA044T-I/MS
24AA04H-I/MS
24AA04HT-I/MS
24AA04-I/MS
24AA04T-I/MS
24AA08H-I/MS
24AA08HT-I/MS
24AA08-I/MS
24AA08T-I/MS
24AA128-I/MS
24AA128T-I/MS
24AA16-E/MS
24AA16H-I/MS
24AA16HT-I/MS
24AA16-I/MS
24AA16T-E/MS
24AA16T-I/MS
24AA256-E/MS
24AA256-I/MS
24AA256-I/MSRVE
24AA256T-E/MS
24AA256T-I/MS
24AA256T-I/MSRVE
24AA32AF-I/MS
24AA32AFT-I/MS
24AA32A-I/MS
24AA32AT-I/MS
24AA64-E/MS
24AA64F-I/MS
24AA64FT-I/MS
24AA64-I/MS
24AA64T-E/MS
24AA64T-I/MS
24FC128-I/MS
24FC128T-I/MS
24FC256-I/MS

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PCN_JAON-15OELO113
CATALOG_PART_NBR
24FC256T-I/MS
24FC64F-I/MS
24FC64FT-I/MS
24FC64-I/MS
24FC64T-I/MS
24LC01B-I/MS
24LC01BT-I/MS
24LC02B-E/MS
24LC02B-I/MS
24LC02BT-E/MS
24LC02BT-I/MS
24LC04B-E/MS
24LC04BH-E/MS
24LC04BH-I/MS
24LC04BHT-E/MS
24LC04BHT-I/MS
24LC04B-I/MS
24LC04BT-E/MS
24LC04BT-I/MS
24LC08B-E/MS
24LC08BH-E/MS
24LC08BH-I/MS
24LC08BHT-E/MS
24LC08BHT-I/MS
24LC08B-I/MS
24LC08BT-E/MS
24LC08BT-I/MS
24LC128-E/MS
24LC128-I/MS
24LC128T-E/MS
24LC128T-I/MS
24LC16B-E/MS
24LC16BH-E/MS
24LC16BH-I/MS
24LC16BHT-E/MS
24LC16BHT-I/MS
24LC16B-I/MS
24LC16BT-E/MS
24LC16BT-I/MS
24LC256-E/MS
24LC256-I/MS
24LC256-I/MSRVF
24LC256T-E/MS

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Affected Catalog Part Numbers (CPN)

PCN_JAON-15OELO113
CATALOG_PART_NBR
24LC256T-I/MS
24LC256T-I/MSRVF
24LC32A-E/MS
24LC32AF-E/MS
24LC32AF-I/MS
24LC32AFT-E/MS
24LC32AFT-I/MS
24LC32A-I/MS
24LC32AT-E/MS
24LC32AT-I/MS
24LC64-E/MS
24LC64F-E/MS
24LC64F-I/MS
24LC64FT-E/MS
24LC64FT-I/MS
24LC64-I/MS
24LC64T-E/MS
24LC64T-I/MS
25AA010A-I/MS
25AA010AT-I/MS
25AA020A-I/MS
25AA020AT-I/MS
25AA040A-I/MS
25AA040AT-I/MS
25AA080A-I/MS
25AA080AT-I/MS
25AA080B-I/MS
25AA080BT-I/MS
25AA080C-I/MS
25AA080CT-I/MS
25AA080D-I/MS
25AA080DT-I/MS
25AA160A-I/MS
25AA160AT-I/MS
25AA160B-I/MS
25AA160BT-I/MS
25AA160C-I/MS
25AA160CT-I/MS
25AA160D-E/MS
25AA160D-I/MS
25AA160DT-E/MS
25AA160DT-I/MS
25AA320A-I/MS

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Affected Catalog Part Numbers (CPN)

PCN_JAON-15OELO113
CATALOG_PART_NBR
25AA320AT-I/MS
25AA640A-E/MS
25AA640A-I/MS
25AA640AT-E/MS
25AA640AT-I/MS
25LC010A-E/MS
25LC010A-I/MS
25LC010AT-E/MS
25LC010AT-I/MS
25LC020A-E/MS
25LC020A-I/MS
25LC020AT-E/MS
25LC020AT-I/MS
25LC040A-E/MS
25LC040A-I/MS
25LC040AT-E/MS
25LC040AT-I/MS
25LC080A-E/MS
25LC080A-I/MS
25LC080AT-E/MS
25LC080AT-I/MS
25LC080B-E/MS
25LC080B-I/MS
25LC080BT-E/MS
25LC080BT-I/MS
25LC080C-E/MS
25LC080C-I/MS
25LC080CT-E/MS
25LC080CT-I/MS
25LC080D-E/MS
25LC080D-I/MS
25LC080DT-E/MS
25LC080DT-I/MS
25LC160A-E/MS
25LC160A-I/MS
25LC160AT-E/MS
25LC160AT-I/MS
25LC160B-E/MS
25LC160B-I/MS
25LC160BT-E/MS
25LC160BT-I/MS
25LC160C-E/MS
25LC160C-I/MS

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PCN_JAON-15OELO113
CATALOG_PART_NBR
25LC160CT-E/MS
25LC160CT-I/MS
25LC160D-E/MS
25LC160D-I/MS
25LC160DT-E/MS
25LC160DT-I/MS
25LC320A-E/MS
25LC320A-I/MS
25LC320AT-E/MS
25LC320AT-I/MS
25LC640A-E/MS
25LC640A-I/MS
25LC640AT-E/MS
25LC640AT-I/MS
93AA46A-I/MS
93AA46AT-I/MS
93AA46B-I/MS
93AA46BT-I/MS
93AA46C-I/MS
93AA46CT-I/MS
93AA56A-I/MS
93AA56AT-I/MS
93AA56B-I/MS
93AA56BT-I/MS
93AA56C-I/MS
93AA56CT-I/MS
93AA66A-I/MS
93AA66AT-I/MS
93AA66B-I/MS
93AA66B-I/MSL21
93AA66BT-I/MS
93AA66BT-I/MSL21
93AA66C-I/MS
93AA66CT-I/MS
93AA76A-I/MS
93AA76AT-I/MS
93AA76B-I/MS
93AA76BT-I/MS
93AA76C-I/MS
93AA76CT-I/MS
93AA86A-I/MS
93AA86AT-I/MS
93AA86B-I/MS

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PCN_JAON-15OELO113
CATALOG_PART_NBR
93AA86BT-I/MS
93AA86C-I/MS
93AA86CT-I/MS
93C46A-E/MS
93C46A-I/MS
93C46AT-E/MS
93C46AT-I/MS
93C46B-E/MS
93C46B-I/MS
93C46BT-E/MS
93C46BT-I/MS
93C46C-E/MS
93C46C-I/MS
93C46CT-E/MS
93C46CT-I/MS
93C56A-E/MS
93C56A-I/MS
93C56AT-E/MS
93C56AT-I/MS
93C56B-E/MS
93C56B-I/MS
93C56BT-E/MS
93C56BT-I/MS
93C56C-E/MS
93C56C-I/MS
93C56CT-E/MS
93C56CT-I/MS
93C66A-E/MS
93C66A-I/MS
93C66AT-E/MS
93C66AT-I/MS
93C66B-E/MS
93C66B-I/MS
93C66BT-E/MS
93C66BT-I/MS
93C66C-E/MS
93C66C-I/MS
93C66CT-E/MS
93C66CT-I/MS
93C76A-E/MS
93C76A-I/MS
93C76AT-E/MS
93C76AT-I/MS

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PCN_JAON-15OELO113
CATALOG_PART_NBR
93C76B-E/MS
93C76B-I/MS
93C76BT-E/MS
93C76BT-I/MS
93C76C-E/MS
93C76C-I/MS
93C76CT-E/MS
93C76CT-I/MS
93C86A-E/MS
93C86A-I/MS
93C86AT-E/MS
93C86AT-I/MS
93C86B-E/MS
93C86B-I/MS
93C86BT-E/MS
93C86BT-I/MS
93C86C-E/MS
93C86C-I/MS
93C86CT-E/MS
93C86CT-I/MS
93LC46A-E/MS
93LC46A-I/MS
93LC46AT-E/MS
93LC46AT-I/MS
93LC46B-E/MS
93LC46B-I/MS
93LC46BT-E/MS
93LC46BT-I/MS
93LC46C-E/MS
93LC46C-I/MS
93LC46CT-E/MS
93LC46CT-I/MS
93LC56A-E/MS
93LC56A-I/MS
93LC56AT-E/MS
93LC56AT-I/MS
93LC56B-E/MS
93LC56B-I/MS
93LC56BT-E/MS
93LC56BT-I/MS
93LC56C-E/MS
93LC56C-I/MS
93LC56CT-E/MS

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PCN_JAON-15OELO113
CATALOG_PART_NBR
93LC56CT-I/MS
93LC66A-E/MS
93LC66A-I/MS
93LC66AT-E/MS
93LC66AT-I/MS
93LC66B-E/MS
93LC66B-I/MS
93LC66BT-E/MS
93LC66BT-I/MS
93LC66C-E/MS
93LC66C-I/MS
93LC66CT-E/MS
93LC66CT-I/MS
93LC76A-E/MS
93LC76A-I/MS
93LC76AT-E/MS
93LC76AT-I/MS
93LC76B-E/MS
93LC76B-I/MS
93LC76BT-E/MS
93LC76BT-I/MS
93LC76C-E/MS
93LC76C-I/MS
93LC76CT-E/MS
93LC76CT-I/MS
93LC86A-E/MS
93LC86A-I/MS
93LC86AT-E/MS
93LC86AT-I/MS
93LC86B-E/MS
93LC86B-I/MS
93LC86BT-E/MS
93LC86BT-I/MS
93LC86C-E/MS
93LC86C-I/MS
93LC86CT-E/MS
93LC86CT-I/MS
MCP1632-AAE/MS
MCP1632-BAE/MS
MCP1632T-AAE/MS
MCP1632T-BAE/MS
MCP3422A0-E/MS
MCP3422A0T-E/MS

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PCN_JAON-15OELO113
CATALOG_PART_NBR
MCP3422A1-E/MS
MCP3422A1T-E/MS
MCP3422A2-E/MS
MCP3422A2T-E/MS
MCP3422A3-E/MS
MCP3422A3T-E/MS
MCP3422A4-E/MS
MCP3422A4T-E/MS
MCP3422A5-E/MS
MCP3422A5T-E/MS
MCP3422A6-E/MS
MCP3422A6T-E/MS
MCP3422A7-E/MS
MCP3422A7T-E/MS
MCP3426A0-E/MS
MCP3426A0T-E/MS
MCP3426A1-E/MS
MCP3426A1T-E/MS
MCP3426A2-E/MS
MCP3426A2T-E/MS
MCP3426A3-E/MS
MCP3426A3T-E/MS
MCP3426A4-E/MS
MCP3426A4T-E/MS
MCP3426A5-E/MS
MCP3426A5T-E/MS
MCP3426A6-E/MS
MCP3426A6T-E/MS
MCP3426A7-E/MS
MCP3426A7T-E/MS
MCP3550-50E/MS
MCP3550-60E/MS
MCP3550T-50E/MS
MCP3550T-60E/MS
MCP3551-E/MS
MCP3551T-E/MS
MCP3553-E/MS
MCP3553T-E/MS
MCP4011-103E/MS
MCP4011-202E/MS
MCP4011-502E/MS
MCP4011-503E/MS
MCP4011T-103E/MS

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PCN_JAON-15OELO113
CATALOG_PART_NBR
MCP4011T-202E/MS
MCP4011T-502E/MS
MCP4011T-503E/MS
MCP4021-103E/MS
MCP4021-202E/MS
MCP4021-502E/MS
MCP4021-503E/MS
MCP4021T-103E/MS
MCP4021T-202E/MS
MCP4021T-502E/MS
MCP4021T-503E/MS
MCP4131-103E/MS
MCP4131-104E/MS
MCP4131-502E/MS
MCP4131-503E/MS
MCP4131T-103E/MS
MCP4131T-104E/MS
MCP4131T-502E/MS
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MCP4132T-104E/MS
MCP4132T-502E/MS
MCP4132T-503E/MS
MCP4141-103E/MS
MCP4141-104E/MS
MCP4141-502E/MS
MCP4141-503E/MS
MCP4141T-103E/MS
MCP4141T-104E/MS
MCP4141T-502E/MS
MCP4141T-503E/MS
MCP4142-103E/MS
MCP4142-104E/MS
MCP4142-502E/MS
MCP4142-503E/MS
MCP4142T-103E/MS
MCP4142T-104E/MS
MCP4142T-502E/MS
MCP4142T-503E/MS

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PCN_JAON-15OELO113
CATALOG_PART_NBR
MCP4151-103E/MS
MCP4151-104E/MS
MCP4151-502E/MS
MCP4151-503E/MS
MCP4151T-103E/MS
MCP4151T-104E/MS
MCP4151T-502E/MS
MCP4151T-503E/MS
MCP4152-103E/MS
MCP4152-104E/MS
MCP4152-502E/MS
MCP4152-503E/MS
MCP4152T-103E/MS
MCP4152T-104E/MS
MCP4152T-502E/MS
MCP4152T-503E/MS
MCP4161-103E/MS
MCP4161-104E/MS
MCP4161-502E/MS
MCP4161-503E/MS
MCP4161T-103E/MS
MCP4161T-104E/MS
MCP4161T-502E/MS
MCP4161T-503E/MS
MCP4162-103E/MS
MCP4162-104E/MS
MCP4162-502E/MS
MCP4162-503E/MS
MCP4162T-103E/MS
MCP4162T-104E/MS
MCP4162T-502E/MS
MCP4162T-503E/MS
MCP4531-103E/MS
MCP4531-104E/MS
MCP4531-502E/MS
MCP4531-503E/MS
MCP4531T-103E/MS
MCP4531T-104E/MS
MCP4531T-502E/MS
MCP4531T-503E/MS
MCP4532-103E/MS
MCP4532-104E/MS
MCP4532-502E/MS

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Affected Catalog Part Numbers (CPN)

PCN_JAON-15OELO113
CATALOG_PART_NBR
MCP4532-503E/MS
MCP4532T-103E/MS
MCP4532T-104E/MS
MCP4532T-502E/MS
MCP4532T-503E/MS
MCP4541-103E/MS
MCP4541-104E/MS
MCP4541-502E/MS
MCP4541-503E/MS
MCP4541T-103E/MS
MCP4541T-104E/MS
MCP4541T-502E/MS
MCP4541T-503E/MS
MCP4542-103E/MS
MCP4542-104E/MS
MCP4542-502E/MS
MCP4542-503E/MS
MCP4542T-103E/MS
MCP4542T-104E/MS
MCP4542T-502E/MS
MCP4542T-503E/MS
MCP4551-103E/MS
MCP4551-104E/MS
MCP4551-502E/MS
MCP4551-503E/MS
MCP4551T-103E/MS
MCP4551T-104E/MS
MCP4551T-502E/MS
MCP4551T-503E/MS
MCP4552-103E/MS
MCP4552-104E/MS
MCP4552-502E/MS
MCP4552-503E/MS
MCP4552T-103E/MS
MCP4552T-104E/MS
MCP4552T-502E/MS
MCP4552T-503E/MS
MCP4561-103E/MS
MCP4561-104E/MS
MCP4561-502E/MS
MCP4561-503E/MS
MCP4561T-103E/MS
MCP4561T-104E/MS

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Affected Catalog Part Numbers (CPN)

PCN_JAON-15OELO113
CATALOG_PART_NBR
MCP4561T-502E/MS
MCP4561T-503E/MS
MCP4562-103E/MS
MCP4562-104E/MS
MCP4562-502E/MS
MCP4562-503E/MS
MCP4562T-103E/MS
MCP4562T-104E/MS
MCP4562T-502E/MS
MCP4562T-503E/MS
MCP4801-E/MS
MCP4801T-E/MS
MCP4802-E/MS
MCP4802T-E/MS
MCP4811-E/MS
MCP4811T-E/MS
MCP4812-E/MS
MCP4812T-E/MS
MCP4821-E/MS
MCP4821T-E/MS
MCP4822-E/MS
MCP4822T-E/MS
MCP4901-E/MS
MCP4901T-E/MS
MCP4911-E/MS
MCP4911T-E/MS
MCP4921-E/MS
MCP4921T-E/MS
MCP6422-E/MS
MCP6422T-E/MS
MCP6472-E/MS
MCP6472T-E/MS
MCP6482-E/MS
MCP6482T-E/MS
MCP6492-E/MS
MCP6492T-E/MS
MCP6N16-001E/MS
MCP6N16-010E/MS
MCP6N16-100E/MS
MCP6N16T-001E/MS
MCP6N16T-010E/MS
MCP6N16T-100E/MS
MCP6V12-E/MS

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Affected Catalog Part Numbers (CPN)

PCN_JAON-15OELO113
CATALOG_PART_NBR
MCP6V12T-E/MS
MCP6V32-E/MS
MCP6V32T-E/MS
MCP6V62-E/MS
MCP6V62T-E/MS
MCP6V72-E/MS
MCP6V72T-E/MS
MCP6V82-E/MS
MCP6V82T-E/MS
MCP6V92-E/MS
MCP6V92T-E/MS
MCP9801-M/MS
MCP9801-M/MSRC2
MCP9801T-M/MS
MCP9801T-M/MSRC2
MCP9803-M/MS
MCP9803-M/MSRC2
MCP9803T-M/MS
MCP9803T-M/MSRC2
MCP9804-E/MS
MCP9804-E/MSBBB
MCP9804T-E/MS
MCP9804T-E/MSBBB
MCP9808-E/MS
MCP9808T-E/MS
PIC12F508-E/MS
PIC12F508-I/MS
PIC12F508T-E/MS
PIC12F508T-I/MS
PIC12F508T-I/MS054
PIC12F508T-I/MS064
PIC12F508T-I/MS076
PIC12F508T-I/MS077
PIC12F509-E/MS
PIC12F509-I/MS
PIC12F509T-E/MS
PIC12F509T-I/MS
PIC12F509T-I/MS029
PIC12F510-E/MS
PIC12F510-I/MS
PIC12F510-I/MSC04
PIC12F510T-E/MS
PIC12F510T-I/MS

JAON-15OELO113 - CCB 2594 Final Notice: Qualification of CuPdAu bond wire in selected products of the 150K and 160K wafer technologies available in 8L MSOP package at MTAI assembly site.

Affected Catalog Part Numbers (CPN)

PCN_JAON-15OELO113
CATALOG_PART_NBR
PIC12F519-E/MS
PIC12F519-I/MS
PIC12F519T-I/MS
PIC12F609-E/MS
PIC12F609-I/MS
PIC12F609T-E/MS
PIC12F609T-I/MS
PIC12F615-E/MS
PIC12F615-H/MS
PIC12F615-I/MS
PIC12F615-I/MSC02
PIC12F615T-E/MS
PIC12F615T-H/MS
PIC12F615T-I/MS
PIC12F615T-I/MS059
PIC12F615T-I/MS063
PIC12F615T-I/MS068
PIC12F615T-I/MS080
PIC12F617-E/MS
PIC12F617-I/MS
PIC12F617-I/MSC04
PIC12F617T-E/MS
PIC12F617T-I/MS
PIC12F617T-I/MS046
PIC12F617T-I/MS056
PIC12F617T-I/MSC04
PIC12HV609-E/MS
PIC12HV609-I/MS
PIC12HV609T-I/MS
PIC12HV615-E/MS
PIC12HV615-I/MS
PIC12HV615T-E/MS
PIC12HV615T-I/MS
TCN75AVUA
TCN75AVUA713



MICROCHIP

**QUALIFICATION REPORT
RELIABILITY LABORATORY**

PCN #: JAON-15OELO113

**Date
May 27, 2016**

**Qualification of palladium coated copper with gold
flash (CuPdAu) bond wire in selected products of the
150K and 160K wafer technologies available in 8L
MSOP package at MTAI assembly site.**

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MICROCHIP **PACKAGE QUALIFICATION REPORT**

Purpose	Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 150K and 160K wafer technologies available in 8L MSOP package at MTAI assembly site.
CN	BC160371
QUAL ID	Q16078
MP CODE	D5AJ5TA3XB00
Part No.	25AA080CT-I/MS
Bonding No.	BDE-002425 Rev. 02
CCB No.	2594
<u>Package</u>	
Type	8L MSOP
Package size	3x3 mm
Die thickness	8 mils
Die size	63.9 x 50.3 mils
<u>Lead Frame</u>	
Paddle size	82 x 94 mils
Material	CDA194
Surface	Bare Cu on DAP
Process	Stamped
Lead Lock	No
Part Number	10100839
Treatment	Brown Oxide Treatment
<u>Die attach material</u>	
Epoxy	8390A
Wire	CuPdAu
Mold Compound	G600V
Plating Composition	Matte Tin



MICROCHIP PACKAGE QUALIFICATION REPORT

Manufacturing Information

Assembly Lot No.	Wafer Lot No.	Date Code
MTAI164902695.000	GRSM416313559.400	1609G86
MTAI164903168.000	GRSM416313559.400	1609HUD
MTAI164903169.000	GRSM416313559.400	1609HUE

Result Pass Fail _____

8L MSOP (3x3 mm) assembled by MTAI pass reliability test per QCI-39000. This package was qualified the Moisture/Reflow Sensitivity Classification Level 1 at 260°C reflow temperature per IPC/JEDEC J-STD-020D standard.

Prepared By: Thinnapol Date: May 27, 2016 (Sr. Reliability Engineer)

(Mr. Thinnapol Nakkasun)

Approved By: Somnuek Date: May 27, 2016 (Reliability Manager)

(Mr. Somnuek Thongprasert)

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS	Result	Remarks
Moisture/Reflow Sensitivity Classification Test (At MSL Level 1)	85 °C/ 85%RH Moisture Soak 168 hrs. System: TABAI ESPEC Model PR-3SPH 3x Convection-Reflow 265°C max System: Vitronics Soltec MR1243 (IPC/JEDEC J-STD-020D)	IPC/JEDEC C J-STD-020D	135	0/135	Pass	

<u>Precondition Prior Perform Reliability Tests (At MSL Level 1)</u>	Electrical Test :+25 °C and 85 °C System: NEXTEST_PT	JESD22-A113	693(0)	693		Good Devices
	Bake 150 °C, 24 hrs System: CHINEE			693		
	85 °C/85%RH Moisture Soak 168 hrs. System: TABAI ESPEC Model PR-3SPH			693		
	3x Convection-Reflow 265 °C max System: Vitronics Soltec MR1243			693		
	Electrical Test :+25 °C and 85 °C System: NEXTEST_PT			0/693	Pass	

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
Temp Cycle	Stress Condition: (Standard) 65°C to +150°C, 500 Cycles System : TABAI ESPEC TSA-70H	JESD22- A104		231		Parts had been pre-conditioned at 260°C 77 units / lot
	Electrical Test: + 85°C System: NEXTEST_PT		231(0)	0/231	Pass	
	Bond Strength: Wire Pull (> 2.5 grams)		15 (0)	0/15	Pass	
	Bond Shear (>15.00 grams)		15 (0)	0/15	Pass	
UNBIASED- HAST	Stress Condition: (Standard) +130°C/85%RH, 96 hrs. System: HAST 6000X	JESD22- A118		231		Parts had been pre-conditioned at 260°C 77 units / lot
	Electrical Test: +25°C System: NEXTEST_PT		231(0)	0/231	Pass	

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
HAST	Stress Condition: (Standard) +130°C/85%RH, 96 hrs. Bias Volt: 5.5 Volts System: HAST 6000X	JESD22-A118		231		Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C and 85°C System: NEXTEST_PT		231(0)	0/231	Pass	77 units / lot
High Temperature Storage Life	Stress Condition: Bake 175°C, 504 hrs System: SHEL LAB	JESD22-A103		45		45 units
	Electrical Test :+25°C and 85°C System: NEXTEST_PT		45(0)	0/45	Pass	
Bond Strength Data Assembly	Wire Pull (>2.5 grams)	M2011	30 (0) Wires	0/30	Pass	
	Bond Shear (>15.00 grams)	JESD22-B116	30 (0) bonds	0/30	Pass	